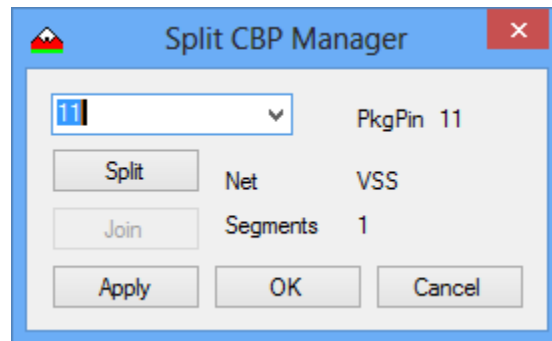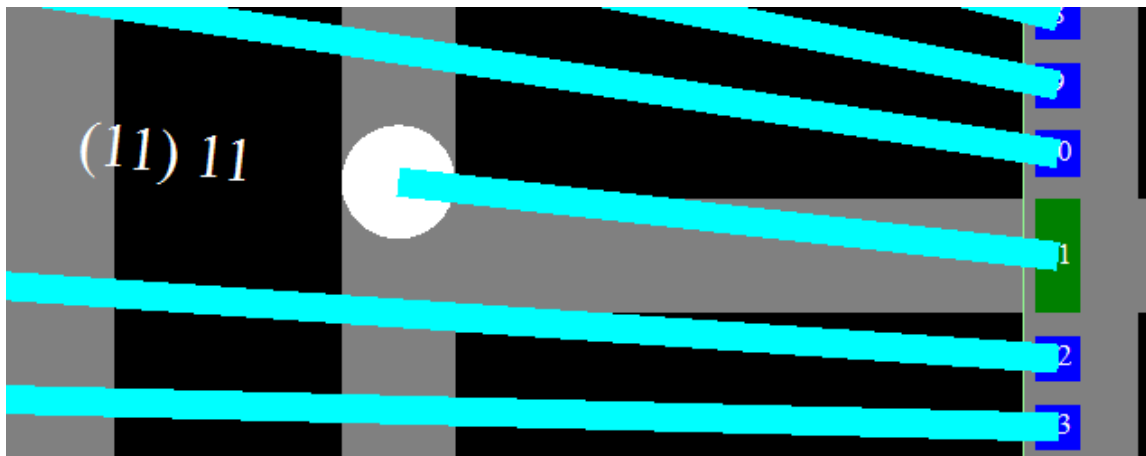# Split CBP Manager

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After running the Demo.kmd you will have the following fanout. I have zoomed into pad 11 since this is the one I will be operating on for this demo. The pad 11 has been modified to be double width in the Demo.pinlist file. The objective is to make this pad a double bonded pad.

Selecting the Split CBP Manager from the Tools menu the following dialog box is displayed. This tool allows you to split a single pad into many segments by clicking on the Split button. Likewise a split pad can be rejoined back into 1 pad segment by clicking the Join button. The number of segments is displayed as well as the Net name and package pin. The original segment is 11 while additional segments are numbered 11.1 (11.2) … for as many segments you split the pad into. Once a split has been executed the CBP wire attach points are located at the center of the pad (0,0)
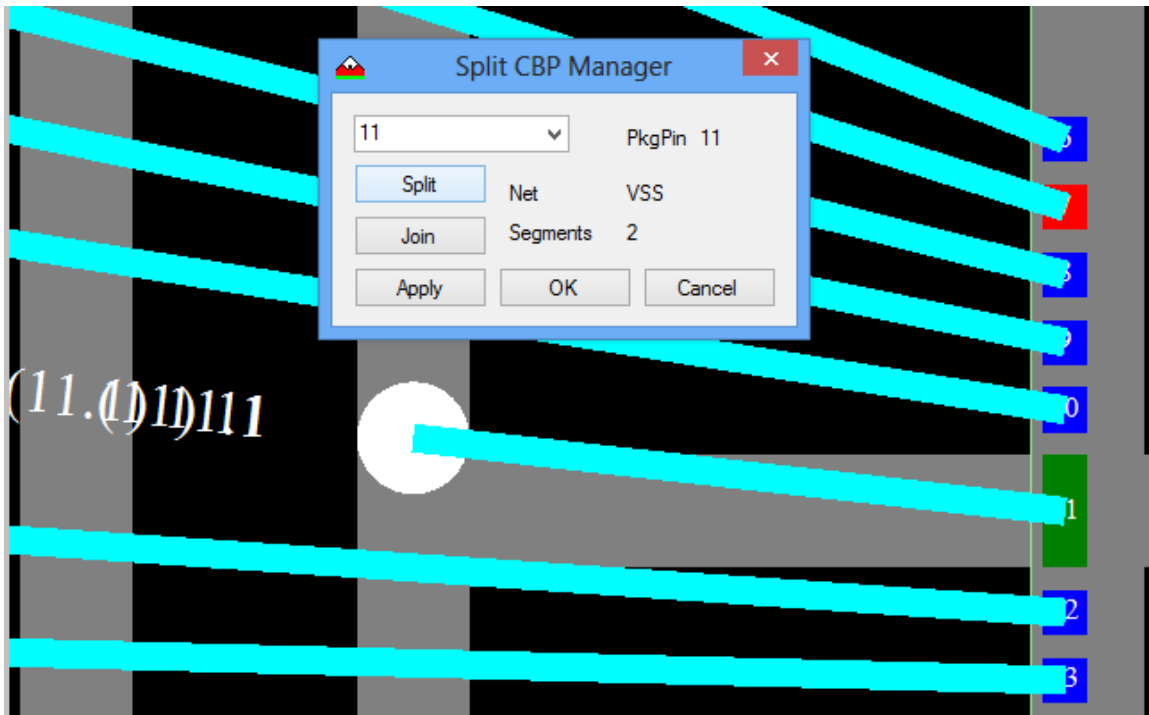
After fanout has been executed again you will see that the 2 segments have been fanned out based on the DRC rules set in the Tiers Properties dialog box. Now the 2 CBP attach points have to be separated.
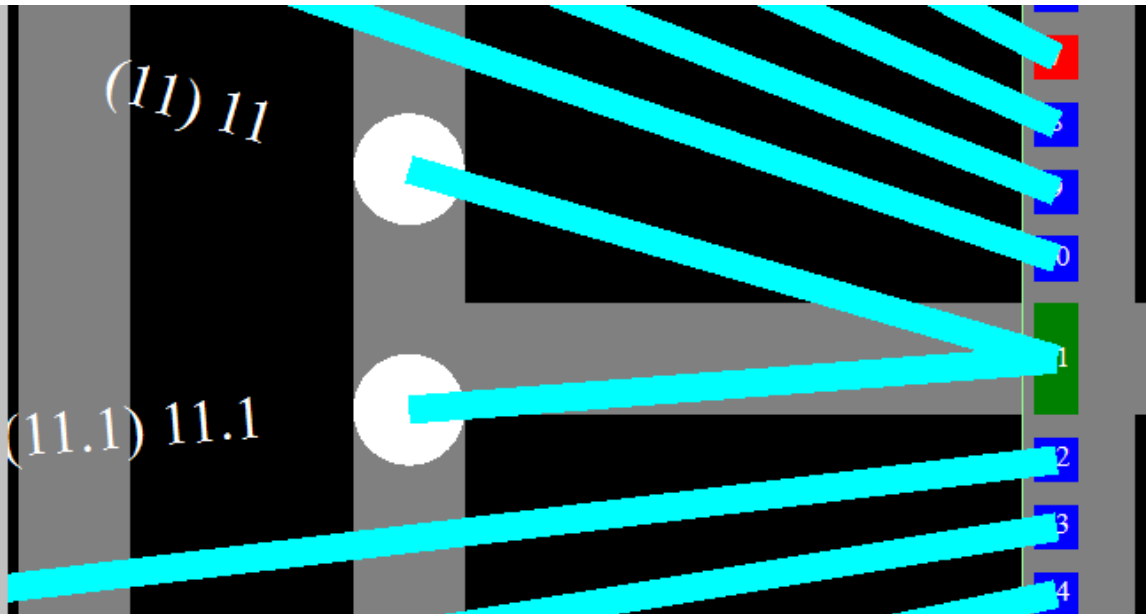

This is done by first selecting the wire or SBP that you want to work on.
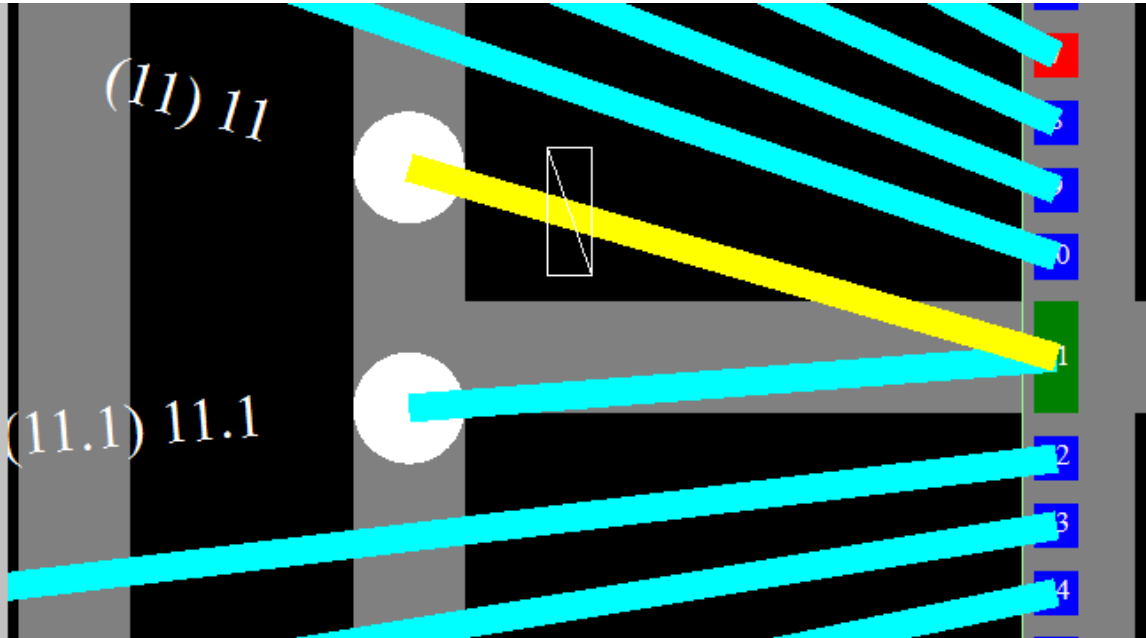
Open the Pad Properties dialog box and the selected wire information will be displayed. In this case I entered 20 into the CBPoffX box and pressed enter to accept the value. Then clicked on the Apply button. As you can see the CBP wire attach point has moved 20 microns to the right. (upward in this case). *Remember the offsets are based on the view at the right of the dialog box.*
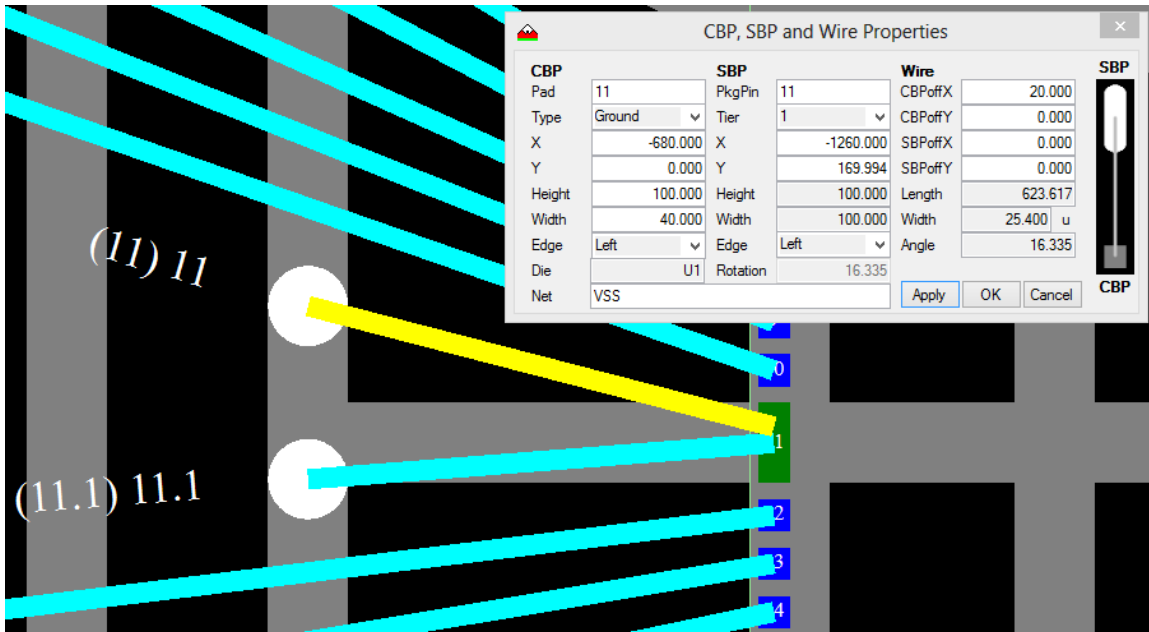
Next select the second segment and set the CBPoffX to –20 and click the Apply button and the CBP wire attach point is moved 20 microns to the left (down in this case).
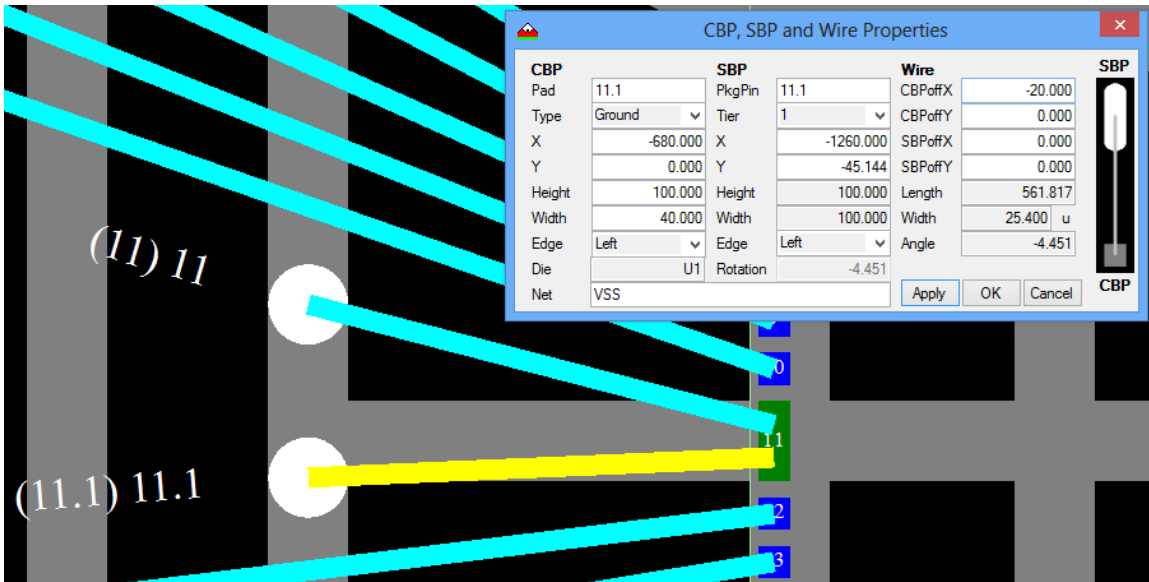
The result of this is pad 11 now has two wires attached to it. (11) 11 and (11.1) 11.1. Since this is in a pad ring you might reduce the Pad to Pad DRC rule for that tier for a tighter design. This depends on the bonding house and what their wire to wire rules are.